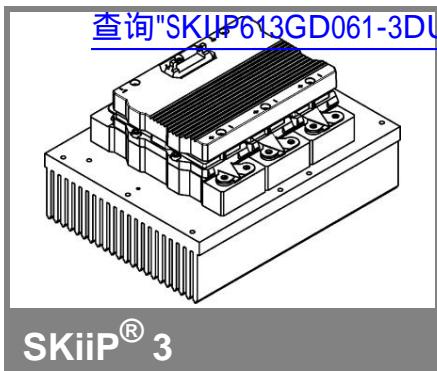


**SKiiP 613GD061-3DUL**



## 6-pack-integrated intelligent power system

## Power section

SKiiP 613GD061-3DUL

## Preliminary Data

## Features

- SKiiP technology inside
  - Low loss IGBTs
  - CAL diode technology
  - Integrated current sensor
  - Integrated temperature sensor
  - Integrated heat sink
  - IEC 60721-3-3 (humidity) class 3K3/IE32 (SKiiP® 3 System)
  - IEC 68T.1 (climate) 40/125/56 (SKiiP® 3 power section)
  - UL recognized file no. E 63 532 (SKiiP® 3 power section)

- 1) with assembly of suitable MKP capacitor per terminal (SEMIKRON type is recommended)

Absolute Maximum Ratings		$T_s = 25^\circ\text{C}$ , unless otherwise specified	
Symbol	Conditions	Values	Units
<b>IGBT</b>			
$V_{CES}$		600	V
$V_{CC}^1)$	Operating DC link voltage	400	V
$V_{GES}$		$\pm 20$	V
$I_C$	$T_s = 25 \text{ (70)}^\circ\text{C}$	600 (450)	A
<b>Inverse diode</b>			
$I_F = -I_C$	$T_s = 25 \text{ (70)}^\circ\text{C}$	560 (420)	A
$I_{FSM}$	$T_j = 150^\circ\text{C}$ , $t_p = 10 \text{ ms}$ ; sin	6000	A
$I^{t^2}$ (Diode)	Diode, $T_j = 150^\circ\text{C}$ , 10 ms	180	$\text{kA}^2\text{s}$
$T_{j^2}$ ( $T_{stg}$ )		- 40 ... + 150 (125)	$^\circ\text{C}$
$V_{isol}$	rms, AC, 1 min	2500	V
$I_{AC\text{-terminal}}$	per AC terminal, rms, $T_s = 70^\circ\text{C}$ ,	400	A
	$T_{\text{terminal}} < 115^\circ\text{C}$		

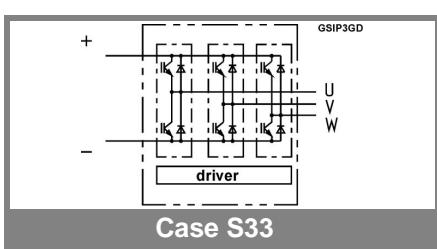
Characteristics		$T_s = 25^\circ\text{C}$ , unless otherwise specified			
Symbol	Conditions	min.	typ.	max.	Units
<b>IGBT</b>					
$V_{CEsat}$	$I_C = 300 \text{ A}, T_j = 25 \text{ (125)}^\circ\text{C};$ measured at terminal		1,5 (1,6)	1,8	V
$V_{CEO}$	$T_j = 25 \text{ (125)}^\circ\text{C};$ at terminal		0,8 (0,7)	1 (0,9)	V
$r_{CE}$	$T_j = 25 \text{ (125)}^\circ\text{C};$ at terminal		2,4 (3,1)	2,7 (3,4)	$\text{m}\Omega$
$I_{CES}$	$V_{GE} = 0 \text{ V}, V_{CE} = V_{CES},$ $T_j = 25 \text{ (125)}^\circ\text{C}$		1,2 (36)		$\text{mA}$
$E_{on} + E_{off}$	$I_C = 300 \text{ A}, V_{CC} = 300 \text{ V}$		27		$\text{mJ}$
	$T_j = 125^\circ\text{C}, V_{CC} = 400 \text{ V}$		39		$\text{mJ}$
$R_{CC+EE'}$	terminal chip, $T_j = 25^\circ\text{C}$		0,5		$\text{m}\Omega$
$L_{CE}$	top, bottom		12		$\text{nH}$
$C_{CHC}$	per phase, AC-side		1,7		$\text{nF}$

<b>Inverse diode</b>				
$V_F = V_{EC}$	$I_F = 300 \text{ A}, T_j = 25 \text{ (125) } ^\circ\text{C}$ measured at terminal		1,3 (1,2)	1,5
$V_{TO}$	$T_j = 25 \text{ (125) } ^\circ\text{C}$	0,8 (0,6)	1 (0,8)	V
$r_T$	$T_j = 25 \text{ (125) } ^\circ\text{C}$	1,5 (1,9)	1,7 (2)	$\text{m}\Omega$
$E_{rr}$	$I_C = 300 \text{ A}, V_{CC} = 300 \text{ V}$	5		$\text{mJ}$
	$T_j = 125 \text{ } ^\circ\text{C}, V_{CC} = 400 \text{ V}$	6		$\text{mJ}$

<b>Mechanical data</b>				
M <sub>dc</sub>	DC terminals, SI Units	6	8	Nm
M <sub>ac</sub>	AC terminals, SI Units	13	15	Nm
w	SKiiP® 3 System w/o heat sink		2,4	kg
w	heat sink		7,5	kg

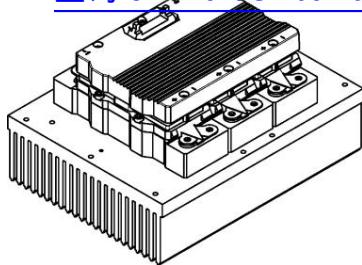
Thermal characteristics (PX16 heat sink with fan SKF16B-230-1); "s" reference to heat sink; "r" reference to built-in temperature sensor (acc.IEC 60747-15)

$R_{th(j-s)I}$	per IGBT								0,059	K/W
$R_{th(j-s)D}$	per diode								0,115	K/W
$Z_{th}$	$R_i$ (mK/W) (max. values)								$\tau_{ai}$ (s)	
	1	2	3	4		1	2	3		4
$Z_{th(j-r)I}$	10,2	28,8	21	0	363	0,18	0,04			1
$Z_{th(j-r)D}$	36	36	54	60	30	5	0,25			0,04
$Z_{th(r-a)}$	2,1	20	5,5	1,4	210	85	11			0,4



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SKiiP® 3

## Absolute Maximum Ratings

Symbol	Conditions	Values	Units
$V_{S2}$	unstabilized 24 V power supply	30	V
$V_i$	input signal voltage (high)	15 + 0,3	V
$dv/dt$	secondary to primary side	75	kV/μs
$V_{isolIO}$	input / output (AC, rms, 2 s)	2500	V
$V_{isolPD}$	partial discharge extinction voltage, rms, $Q_{PD} \leq 10 \text{ pC}$ ;	960	V
$V_{isol12}$	output 1 / output 2 (AC, rms, 2 s)	1500	V
f	switching frequency	20	kHz
$T_{op} (T_{stg})$	operating / storage temperature	- 40 ... + 85	°C

## 6-pack-integrated intelligent power system

6-pack  
integrated gate driver  
SKiiP 613GD061-3DUL

Preliminary Data

### Gate driver features

- CMOS compatible inputs
- Wide range power supply
- Integrated circuitry to sense phase current, heat sink temperature and DC-bus voltage (option)
- Short circuit protection
- Over current protection
- Over voltage protection (option)
- Power supply protected against under voltage
- Interlock of top/bottom switch
- Isolation by transformers
- Fibre optic interface (option for GB-types only )
- IEC 68T.1 (climate) 40/85/56 (SKiiP® 3 gate driver)

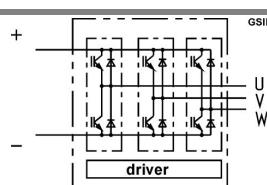
## Characteristics

Symbol	Conditions	min.	typ.	max.	Units
$V_{S2}$	supply voltage non stabilized	13	24	27	V
$I_{S2}$	$V_{S2} = 24 \text{ V}$	$375+30*f/\text{kHz}+0,00111*(I_{AC}/A)^2$			mA
$V_{IT+}$	input threshold voltage (High)	11,2			V
$V_{IT-}$	input threshold voltage (Low)		5,4		V
$R_{IN}$	input resistance	10			kΩ
$C_{IN}$	input capacitance	1			nF
$t_{d(on)IO}$	input-output turn-on propagation time	1,1			μs
$t_{d(off)IO}$	input-output turn-off propagation time	1,1			μs
$t_{pERRRESET}$	error memory reset time	9			μs
$t_{TD}$	top / bottom switch interlock time	3,3			μs
$I_{analogOUT}$	max. 5 mA; 8 V corresponds to 15 V supply voltage for external components	600			A
$I_{s1out}$	max. load current		50		mA
$I_{TRIPSC}$	over current trip level ( $I_{analog OUT} = 10 \text{ V}$ )		750		A
$T_{tp}$	over temperature protection	110		120	°C
$U_{DCTRIP}$	$U_{DC}$ -protection ( $U_{analog OUT} = 9 \text{ V}$ ); (option for GB type)		400		V

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Case S33